

General Description

The WSP09N10T is the highest performance trench Dual N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The WSP09N10T meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

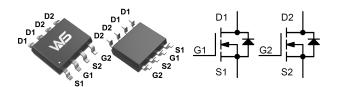
Product Summery

BVDSS	RDSON	ID
100V	70mΩ	5.8A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOP-8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V_{DS}	Drain-Source Voltage	100	V	
V_{GS}	Gate-Source Voltage	±20	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	5.8	Α	
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	4.7	Α	
I _{DM}	Pulsed Drain Current ²	25	Α	
EAS	Single Pulse Avalanche Energy ³	25	mJ	
I _{AS}	Avalanche Current	10	Α	
P _D @T _A =25℃	Total Power Dissipation ³	2.5	W	
T _{STG}	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	℃	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹(t≤10s)		50	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹ (steady state)		90	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.098		V/℃
В	Static Drain-Source On-Resistance ²	V_{GS} =10V , I_D =3.5A		70	100	mΩ
R _{DS(ON)}		V _{GS} =4.5V , I _D =3A		90	120	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/ -250A	1.2	2	3.0	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-4.57		mV/℃
		V _{DS} =80V , V _{GS} =0V , T _J =25℃			1	- uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =55℃			5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =2A		20		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.5		Ω
Q_g	Total Gate Charge (10V)	V _{DS} =30V , V _{GS} =10V , I _D =3.5A		16		
Q_{gs}	Gate-Source Charge			2.5		nC
Q_{gd}	Gate-Drain Charge			3.0		
T _{d(on)}	Turn-On Delay Time			11		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		6		
T _{d(off)}	Turn-Off Delay Time	$R_G=6\Omega$ $I_D=1A$, $R_L=30\Omega$		27		ns
T _f	Fall Time			5		
C _{iss}	Input Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		740		
C _{oss}	Output Capacitance			45		pF
C _{rss}	Reverse Transfer Capacitance			24		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =25V , L=0.5mH , I _{AS} =10A	20			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			3	Α
I _{SM}	Pulsed Source Current ^{2,6}				14	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_S =3A , T_J =25 $^{\circ}{\mathbb{C}}$			1.1	V
t _{rr}	Reverse Recovery Time	lF=3A,dl/dt=100A/μs,T _J =25℃		27		nS
Q _{rr}	Reverse Recovery Charge			36		nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, t<10sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.5mH, I_{AS} =10A
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

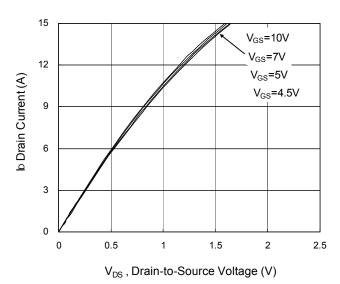


Fig.1 Typical Output Characteristics

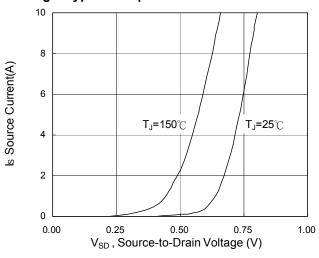


Fig.3 Forward Characteristics Of Reverse

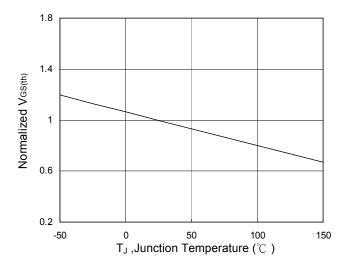


Fig.5 Normalized $V_{\text{GS}(\text{th})}$ vs. T_{J}

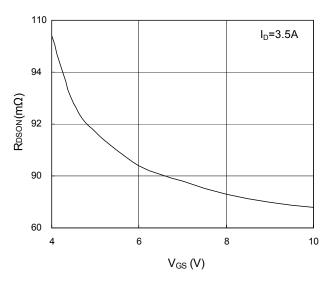


Fig.2 On-Resistance vs. Gate-Source

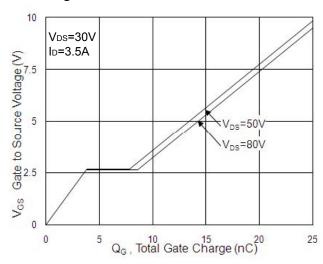


Fig.4 Gate-Charge Characteristics

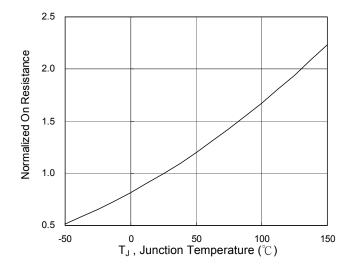
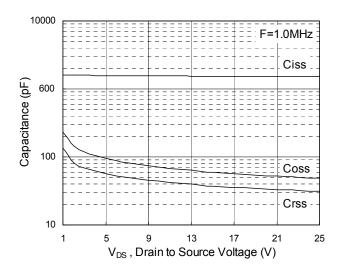


Fig.6 Normalized R_{DSON} vs. T_{J}





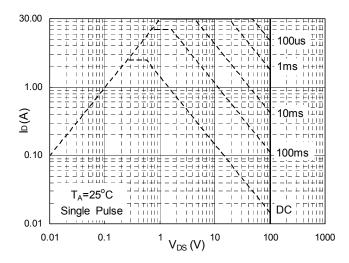


Fig.7 Capacitance

Fig.8 Safe Operating Area

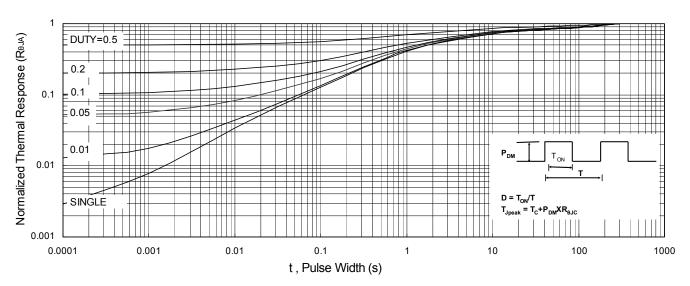


Fig.9 Normalized Maximum Transient Thermal Impedance

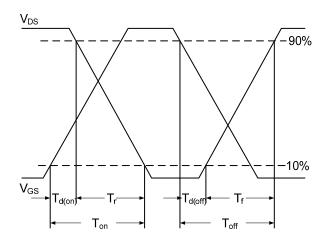


Fig.10 Switching Time Waveform

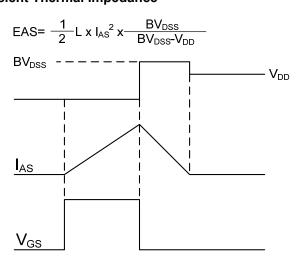


Fig.11 Unclamped Inductive Switching Waveform



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